

EPO-TEK®

World Class LED Adhesives

Heat Sink Attach Electrically & Thermally Conductive

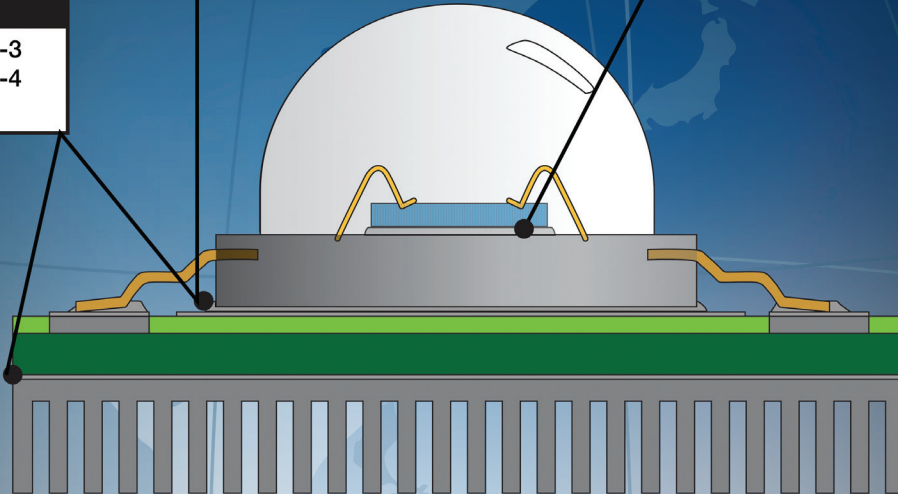
- EK1000
- EK2000
- H20E

Heat Sink Attach Thermally Conductive

- 930-4
- H70E
- T7109
- T905BN-3
- T905BN-4
- TD1001

Die Attach Electrically & Thermally Conductive

- EK1000
- EK2000
- H20E

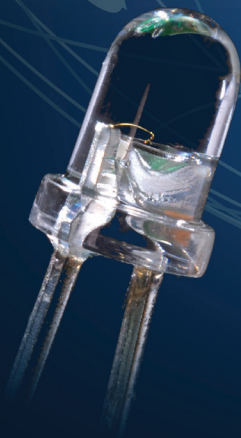


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- Unsurpassed Thermal and Electrical Management
- Proven Quality and Reliability

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Die Attach

Electrically and Thermally Conductive

| EPO-TEK® | Cure Temperature (minimal) | Viscosity @ 23°C (cPs) | Volume Resistivity (ohm-cm) | Thermal Conductivity (W/m²K) | Performance Features |
|------------------|----------------------------------|-------------------------|-----------------------------|---|---|
| EK1000 EK2000 | 200°C - 30 min | 1,800 - 3,600 @ 100 rpm | <0.00009 | 12.6 (150°C/1hr cure) 26.3 (200°C/1hr post-cure) | Single or two component adhesive exhibiting exceptional thermal and electrical conductivity. Ideal for high power LEDs. |
| H20E | 175°C - 45 sec 80°C - 3 hours | 2,200 - 3,200 @ 100 rpm | ≤0.0004 | 2.5 | Two component adhesive with proven reliability in low power LEDs. |

Heat Sink Attach

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Thermally Conductive

| | | | | | |
|----------|----------------------------------|--------------------------|-----------------------|-----------------------------|---|
| 930-4 | 150°C - 10 min 80°C - 6 hours | 12,000 - 17,000 @ 20 rpm | ≥2 x 10 ¹³ | 1.67 | Two component adhesive providing excellent heat dissipation and insulating properties. |
| H70E | 175°C - 1 min 80°C - 90 min | 4,000 - 7,000 @ 50 rpm | ≥1 x 10 ¹³ | 0.9 | Two component, fast curing adhesive recommended for thermal management applications. |
| T7109 | 150°C - 10 min 80°C - 8 hours | 14,000 - 20,000 @ 20 rpm | ≥8 x 10 ¹² | 0.7 (40 mil) 1.5 (3 mil) | Two component, low stress adhesive designed for large bond area die attach and heat sinking applications. |
| T905BN-3 | 80°C - 2 hours | 2,000 - 7,000 @ 50 rpm | 3 x 10 ¹¹ | 2.02 | Two component adhesive with high thermal conductivity designed for heat sinking and encapsulation. |
| T905BN-4 | 80°C - 1 hour 23°C - 1 day | 12,000 - 18,000 @ 20 rpm | ≥4 x 10 ¹⁴ | 1.78 | Two component room temperature curing adhesive with pure white color for easy inspection. |
| TD1001 | 125°C - 1 hour | 10,000 - 22,000 @ 5 rpm | ≥2 x 10 ¹³ | 0.77 | Single component, white adhesive with low T _g and long pot life for low stress packaging. |



Please consult our *Application Experts* at Epoxy Technology to find the most suitable adhesives for specific technical challenges at: techserv@epotek.com.

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EPO-202-01

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